



Tri-Band HBT Power Amplifier Module


AP134-501

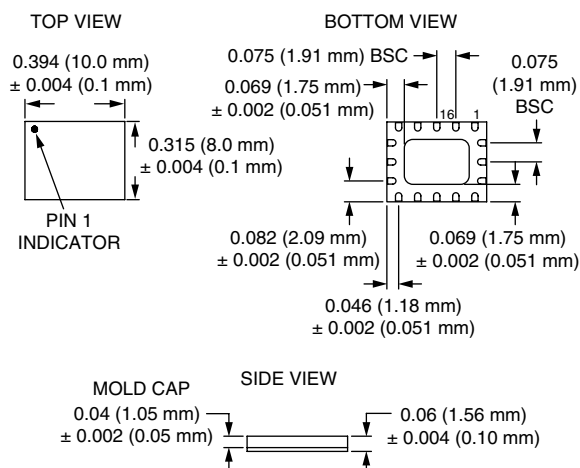
Features

- 3.2 V Nominal Operating Voltage
- 50 Ω Internally Matched Input and Output
- High Power Added Efficiency: 55% for GSM and 50% for DCS and PCS
- Small Size: 10 x 8 x 1.6 mm MCM Land Grid Array Package
- Low Current Standby Mode: < 10 μ A
- Integral Band Select and Analog Power Control
- GPRS Class 12 Capable

Description

The AP134-501 is a high performance IC power amplifier module designed for use as the final amplification stage in tri-band GSM and GPRS mobile phone applications (880–915, 1710–1785 and 1850–1910 MHz). It features 3-cell battery operation, a band select switch, a single positive analog power control input for both bands, and exceptional power added efficiency. The amplifier is manufactured on an advanced InGaP HBT process, known industry-wide for its excellent reliability and performance. The amplifier module is completely self-contained, requiring no external matching components.

-501



Absolute Maximum Ratings

Characteristic	Value
Supply Voltage V_{CC} , Standby Mode, $V_{APC} < 0.3$, No RF Input Power	6 V
Power Control Voltage	4 V
Band Select Voltage	4 V
Input Power (CW)	15 dBm
Operating Case Temperature	-35 to +85°C
Storage Temperature	-45 to 120°C

DC Specifications

Parameter	Condition	Min.	Typ.	Max.	Unit
Supply Voltage		2.8	3.2	4.2	V
Leakage Current	No RF Input Power			10	μ A
Band Select Voltage	GSM	0		0.5	V
	DCS/PCS	2.0		2.8	V
Band Select Current				1.0	mA
Power Control Voltage		0.1		1.9	V
Power Control Current				1.0	mA

Electrical Specifications

GSM Mode

Parameter	Condition	Min.	Typ.	Max.	Unit
Frequency		880		915	MHz
Output Power		34	35		dBm
	$V_{CC} = 2.8 \text{ V}$, $T = -20 \text{ to } +70^\circ\text{C}$	32.5			dBm
Dynamic Range	$V_{APC} = 0.1\text{--}1.9 \text{ V}$	60			dB
Power Control Slope	$V_{APC} = 0.1\text{--}1.9 \text{ V}$		75	150	dB/ V_{APC}
Power Added Efficiency	$P_{OUT} = 34 \text{ dBm}$	50	55		%
Input Power		3	6	10	dBm
Input VSWR	$P_{OUT} = 5\text{--}35 \text{ dBm}$			2:1	
Forward Isolation	$P_{IN} = -5 \text{ dBm}$, $V_{APC} = 0.1 \text{ V}$			-40	dBm
	$P_{IN} = 10 \text{ dBm}$, $V_{APC} = 0.1 \text{ V}$			-25	dBm
Harmonics	$2 F_0 \dots 7 F_0$			-10	dBm
Noise in the R_X Band	925 MHz, 100 KHz BW			-72	dBm
	935 MHz, 100 KHz BW			-84	dBm
	1805–1880 MHz, 100 KHz BW			-76	dBm
	1930–1990 MHz, 100 KHz BW			-76	dBm
Ruggedness	Output VSWR = 10:1 All Phase Angles, $V_{CC} = 4.2 \text{ V}$, $P_{IN} = 10 \text{ dBm}$, $V_{APC} = 1.9 \text{ V}$	No Module Damage or Permanent Performance Degradation			
Stability	Output VSWR = 10:1 All Phase Angles, $V_{CC} = 4.2 \text{ V}$, $P_{IN} = 10 \text{ dBm}$, $V_{APC} = 1.9 \text{ V}$			-36	dBm
Band to Band Isolation	$2 F_0$ Measured at DCS Output			-20	dBm
	$3 F_0$ Measured at DCS Output			-20	dBm

Unless otherwise stated: pulsed operation @ 12.5% duty cycle, 50 Ω system, $V_{CC} = 3.2 \text{ V}$, $P_{IN} = 6 \text{ dBm}$ and temperature = 25°C

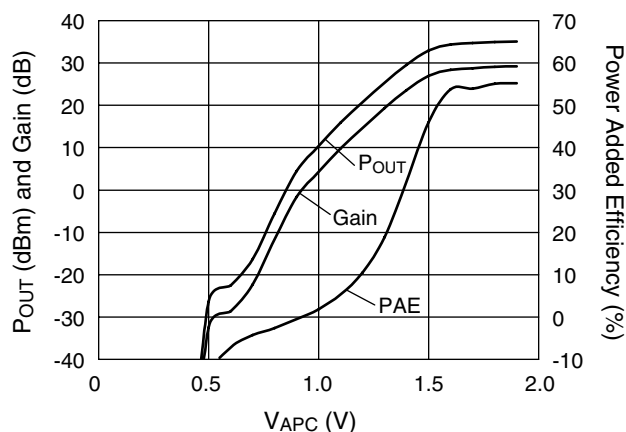
DCS/PCS Mode

Parameter	Condition	Min.	Typ.	Max.	Unit
Frequency	DCS	1710		1785	MHz
	PCS	1850		1910	MHz
Output Power		31.9	32.5		dBm
	$V_{CC} = 2.8 \text{ V}$, $T = -20 \text{ to } +70^\circ\text{C}$	29.5			dBm
Dynamic Range	$V_{APC} = 0.1\text{--}1.9 \text{ V}$	60			dB
Power Control Slope	$V_{APC} = 0.1\text{--}1.9 \text{ V}$		75	150	dB/ V_{APC}
Power Added Efficiency	$P_{OUT} = 31.9 \text{ dBm}$	42	50		%
Input Power		3	6	10	dBm
Input VSWR	$P_{OUT} = 0\text{--}32 \text{ dBm}$			2:1	
Forward Isolation	$P_{IN} = -5 \text{ dBm}$, $V_{APC} = 0.1 \text{ V}$			-48	dBm
	$P_{IN} = 10 \text{ dBm}$, $V_{APC} = 0.1 \text{ V}$			-20	dBm
Harmonics	$2 F_0 \dots 7 F_0$			-10	dBm
Noise in the R_X Band	1805–1880 MHz, 100 KHz BW			-76	dBm
Ruggedness	Output VSWR = 10:1 All Phase Angles, $V_{CC} = 4.2 \text{ V}$, $P_{IN} = 10 \text{ dBm}$, $V_{APC} = 1.9 \text{ V}$	No Module Damage or Permanent Performance Degradation			
Stability	Output VSWR = 10:1 All Phase Angles, $V_{CC} = 4.2 \text{ V}$, $P_{IN} = 10 \text{ dBm}$, $V_{APC} = 1.9 \text{ V}$			-36	dBm

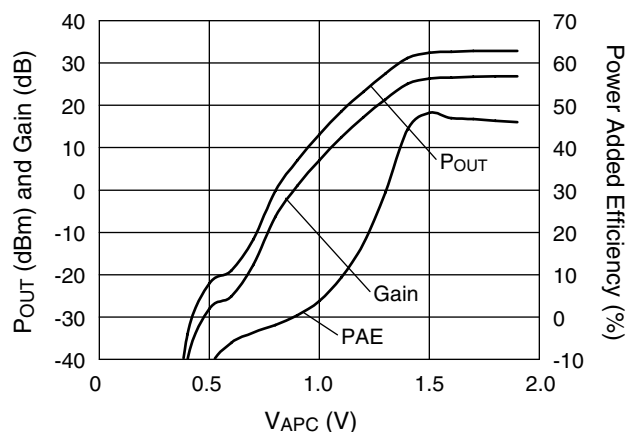
Unless otherwise stated: pulsed operation @ 12.5% duty cycle, 50 Ω system, $V_{CC} = 3.2 \text{ V}$, $P_{IN} = 6 \text{ dBm}$ and temperature = 25°C

Typical Performance Data

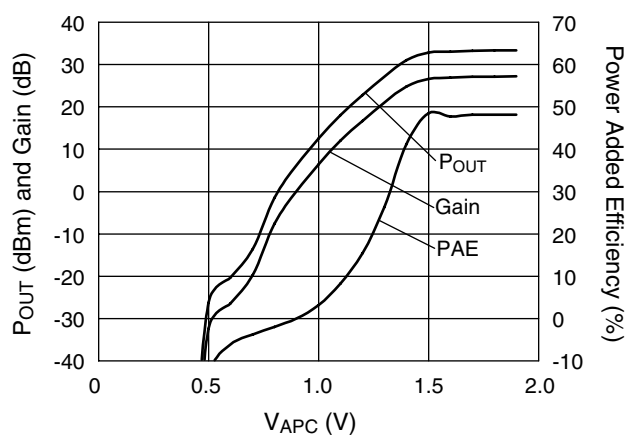
All data taken under CW conditions and include 0.2 dB of input and output fixture losses deembedded, GSM class 4 pulsed performance adds 0.5 dB of output power and 5–7% in PAE.



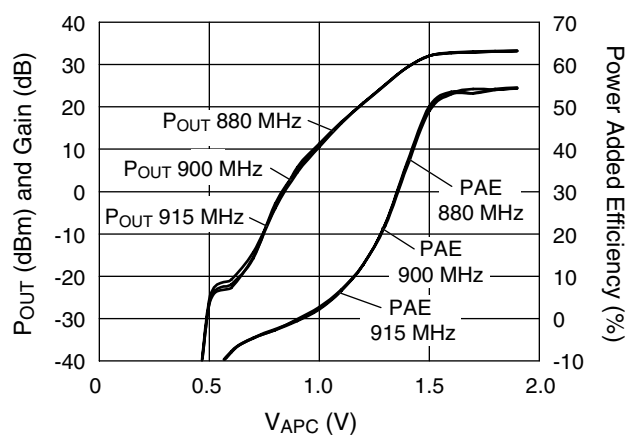
$V_{CC} = 3.2$ V, Frequency = 900 MHz,
 $P_{IN} = 6$ dBm



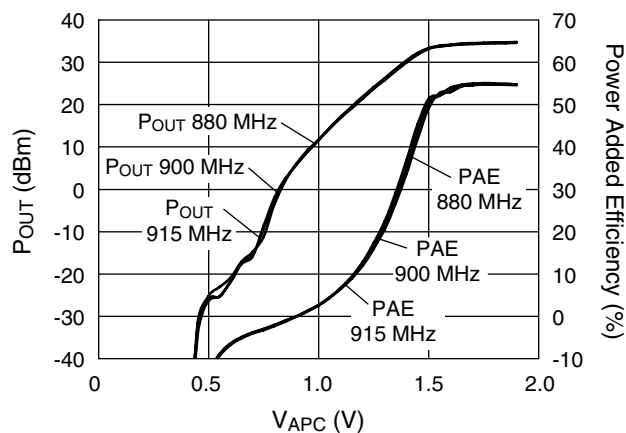
$V_{CC} = 3.2$ V, Frequency = 1750 MHz,
 $P_{IN} = 6$ dBm



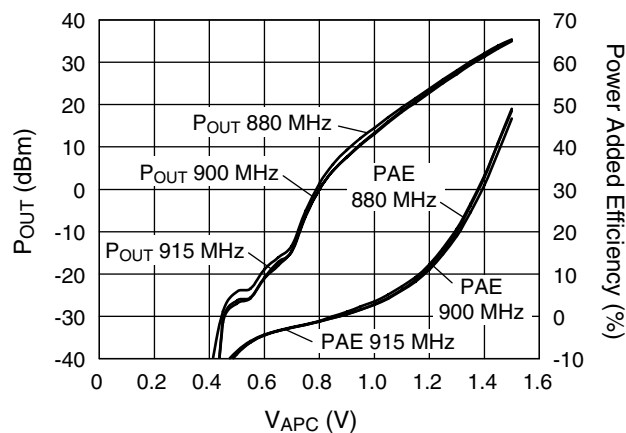
$V_{CC} = 3.2$ V, Frequency = 1910 MHz,
 $P_{IN} = 6$ dBm



$V_{CC} = 2.8$ V, Frequency = 900 MHz,
 $P_{IN} = 6$ dBm

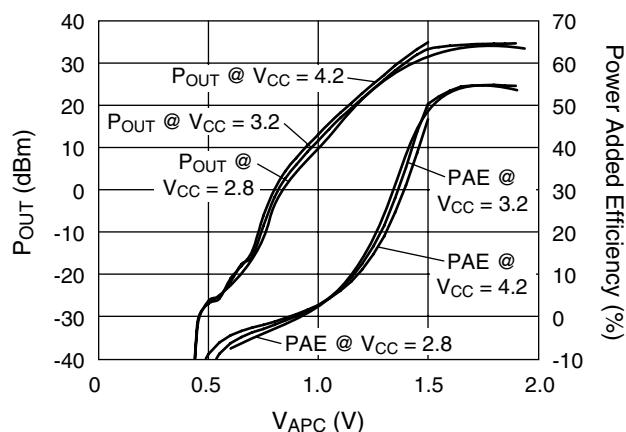


P_{OUT} and PAE vs. V_{APC} and
Frequency, $V_{CC} = 3.2$ V, $P_{IN} = 6$ dBm

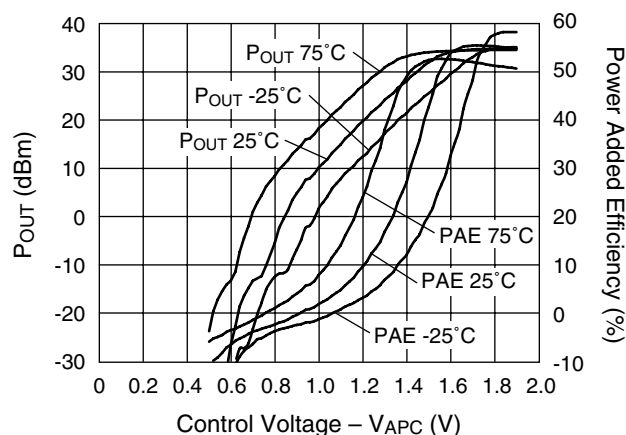


P_{OUT} and PAE vs. V_{APC}
and Frequency, $V_{CC} = 4.2$ V, $P_{IN} = 6$ dBm

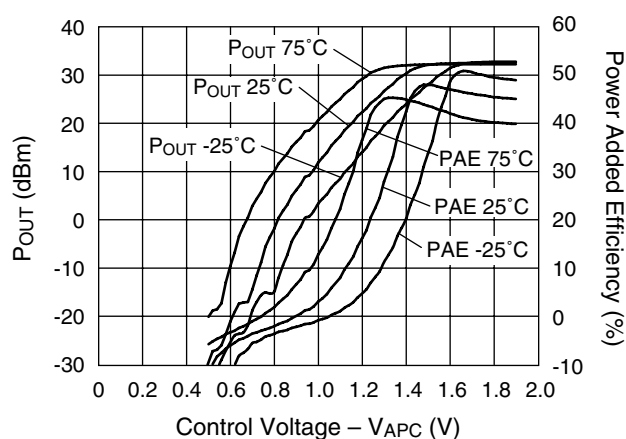
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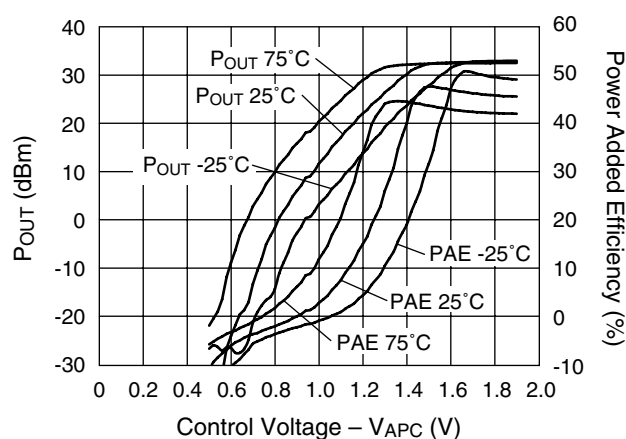
POUT and PAE vs. V_{CC} and V_{APC}
 $P_{IN} = 6$ dBm



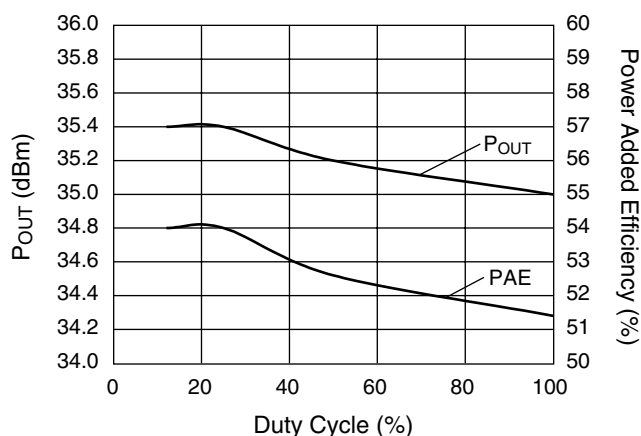
POUT and PAE vs. Temperature
 $V_{CC} = 3.2$ V, $P_{IN} = 6$ dBm,
 Frequency = 880 MHz



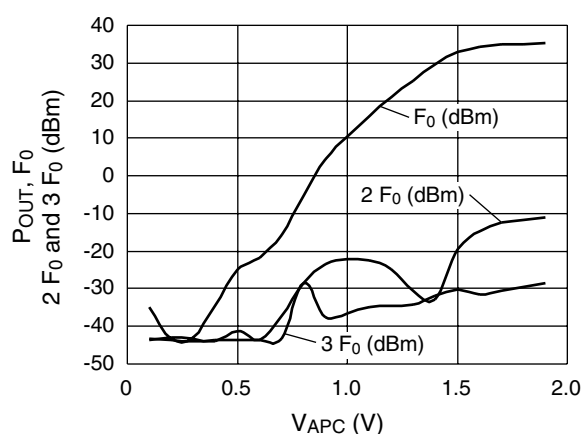
POUT and PAE vs. Temperature
 $V_{CC} = 3.2$ V, $P_{IN} = 6$ dBm,
 Frequency = 1710 MHz



POUT and PAE vs. Temperature
 $V_{CC} = 3.2$ V, $P_{IN} = 6$ dBm,
 Frequency = 1850 MHz

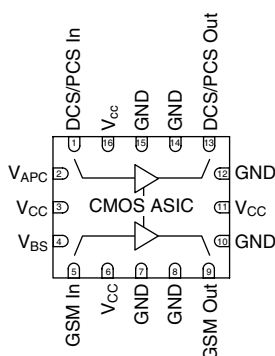


Duty Cycle Effects on Module Performance
 $V_{CC} = 3.2$ V, Frequency = 900 MHz,
 $P_{IN} = 6$ dBm



Harmonic Performance $V_{CC} = 3.2$ V,
 Frequency = 900 MHz, $P_{IN} = 6$ dBm

Pin Out



Pin Out Description

Pin	Symbol	Description
1	DCS/PCS_In	RF input to DCS/PCS power amplifier.
2	V _{APC}	Analog power control input voltage. 10 nF RF bypassing capacitor recommended.
3	V _{CC}	Power supply input voltage. A 10 μ F RF bypassing capacitor is required. This capacitor is only required to help reduce power supply ripple on the test board.
4	V _{BS}	Band select input voltage.
5	GSM_In	RF input to GSM power amplifier.
6	V _{CC}	Power supply input voltage. 10 μ F RF bypassing capacitor is required. This capacitor is only required to help reduce power supply ripple on the test board.
7	GND	Ground connection.
8	GND	Ground connection.
9	GSM_Out	RF output for GSM amplifier.
10	GND	Ground connection.
11	V _{CC}	Power supply input voltage. 10 μ F RF bypassing capacitor is required. This capacitor is only required to help reduce power supply ripple on the test board.
12	GND	Ground connection.
13	DCS/PCS_Out	RF output for DCS/PCS power amplifier.
14	GND	Ground connection.
15	GND	Ground connection.
16	V _{CC}	Power supply input voltage. 10 μ F RF bypassing capacitor is required. This capacitor is only required to help reduce power supply ripple on the test board.

Application Schematic

